

15A, 600V - 1000V Standard Bridge Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for printed circuit board
- Typical IR less than 0.1μA
- High surge current capability
- UL Recognized File # E-326243
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application

MECHANICAL DATA

• Case: TS-6P

• Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

Mounting torque: 0.92 N·m maximum

Polarity: As marked

• Weight: 6.50g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _F	15	Α		
V_{RRM}	600 - 1000	V		
I _{FSM}	240	Α		
T_{JMAX}	150 °C			
Package	TS-6P			
Configuration	Quad			







TS-6P

PARAMETER	SYMBOL	TS15P05G-K	TS15P06G-K	TS15P07G-K	UNIT
Marking code on the device		TS15P05G	TS15P06G	TS15P07G	
Repetitive peak reverse voltage	V_{RRM}	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	420	560	700	V
Forward current	I _F	15			Α
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	240			А
Rating of fusing (t<8.3ms)	l ² t	239.04			A ² s
Junction temperature	TJ	- 55 to +150			°C
Storage temperature	T _{STG}	- 55 to +150			°C



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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	TINU		
Junction-to-case thermal resistance	R _{eJC}	1.3	°C/W		

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode ⁽¹⁾	I _F = 7.5A, T _J = 25°C	V _F	1	1.0	V
	I _F = 7.5A, T _J = 125°C		-	0.9	V
Reverse current @ rated V _R per diode ⁽²⁾	T _J = 25°C	I _R	1	10	μΑ
	T _J = 125°C		-	500	μA
Junction capacitance per diode	1MHz, V _R = 4.0V	CJ	73	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION					
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING			
TS15PxG-K	TS-6P	15 / Tube			

Notes:

1. "x" defines voltage from 600V(TS15P05G-K) to 1000V(TS15P07G-K)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

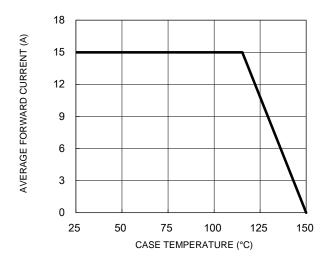


Fig.3 Typical Reverse Characteristics

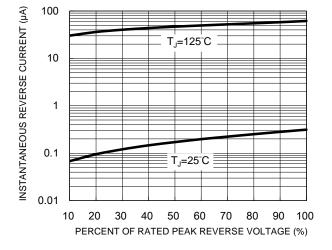


Fig.2 Typical Junction Capacitance

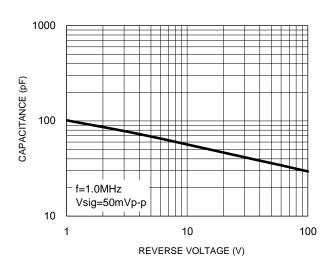
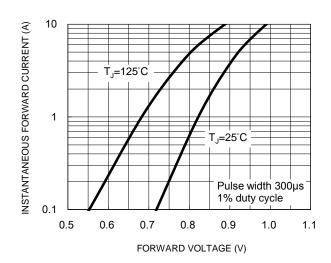


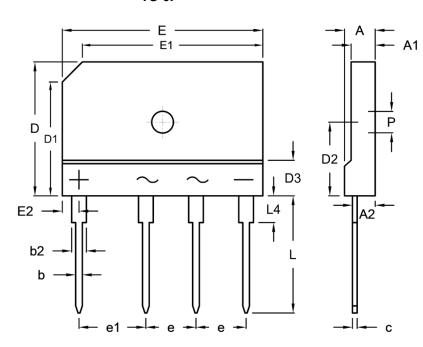
Fig.4 Typical Forward Characteristics





PACKAGE OUTLINE DIMENSIONS

TS-6P



DIM. Unit (mm)		(mm)	Unit ((inch)
DIIVI.	Min.	Max.	Min.	Max.
Α	4.40	4.80	0.173	0.189
A1	3.40	3.80	0.134	0.150
A2	3.10	3.70	0.122	0.146
b	0.90	1.10	0.035	0.043
b2	2.00	2.40	0.079	0.094
С	0.60	0.80	0.024	0.031
D	19.70	20.30	0.776	0.799
D1	16.50	17.50	0.650	0.689
D2	10.80	11.20	0.425	0.441
D3	4.80	5.80	0.189	0.228
E	29.70	30.30	1.169	1.193
E1	26.50	27.50	1.043	1.083
E2	2.30	2.70	0.091	0.106
е	7.30	7.70	0.287	0.303
e1	9.80	10.20	0.386	0.402
L	17.00	18.00	0.669	0.709
L4	3.80	4.20	0.150	0.165
Р	3.10	3.40	0.122	0.134

MARKING DIAGRAM



P/N = Marking Code

G = Green Compound

YWW = Date Code

= Factory Code



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